Product Change Notification: CENO-13CPHA326

Date:

16-Oct-2024

Product Category:

AC/DC - Inductorless Offline Controllers, EL Backlight Driver ICs, General Purpose LED Drivers, Inductorless Off-Line Regulator Ics, Linear Regulator Ics

Notification Subject:

CCB 7197 Final Notice: Qualification of MMT as an additional assembly site for HV9925SG-G, SR037SG-G, SR036SG-G, CL320SG-G, CL7SG-G, SR087SG-G, SR086SG-G, HV809SG-G, CL325SG-G and CL330SG-G catalog part numbers (CPN) available in 8L SOIC (3.90mm) package.

Affected CPNs:

CENO-13CPHA326_Affected_CPN_10162024.pdf
CENO-13CPHA326_Affected_CPN_10162024.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MMT as an additional assembly site for HV9925SG-G, SR037SG-G, SR036SG-G, CL320SG-G, CL7SG-G, SR087SG-G, SR086SG-G, HV809SG-G, CL325SG-G and CL330SG-G catalog part numbers (CPN) available in 8L SOIC (3.90mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change	
Assembly Site	Unisem (M) Berhad Perak, Malaysia	Unisem (M) Berhad Perak, Malaysia (UNIS)	Microchip Technology Thailand (Branch) (MMT)

	(UNIS)		
Wire Material	Au	Au	Au
Die Attach Material	8290	8290	8390A
Molding Compound Material	EME-G600	EME-G600	G600V
Lead-Frame Material	A194	A194	A194
DAP Surface Prep	Ag Spot Plated	Ag Spot Plated	Ag Ring Plated
	See Pre and Post Change for comparison.		

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying MMT as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 11 December 2024 (date code: 2450)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	October 2024					>	**December 2024**				
Work Week	40	41	42	43	44		49	50	51	52	01
Qual Report Availability			X								
Final PCN Issue Date			X								

Estimated Implementation Date								X			

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: October 16, 2024: Issued final notification

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_CENO-13CPHA326_Qual report.pdf
PCN_CENO-13CPHA326_Pre and Post Change_Summary.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

HV9925SG-G
SR037SG-G
SR036SG-G
CL320SG-G
CL7SG-G
SR087SG-G
SR086SG-G
HV809SG-G
CL325SG-G
CL330SG-G

CCB 7197
Pre and Post Change Summary
PCN #: CENO-13CPHA326

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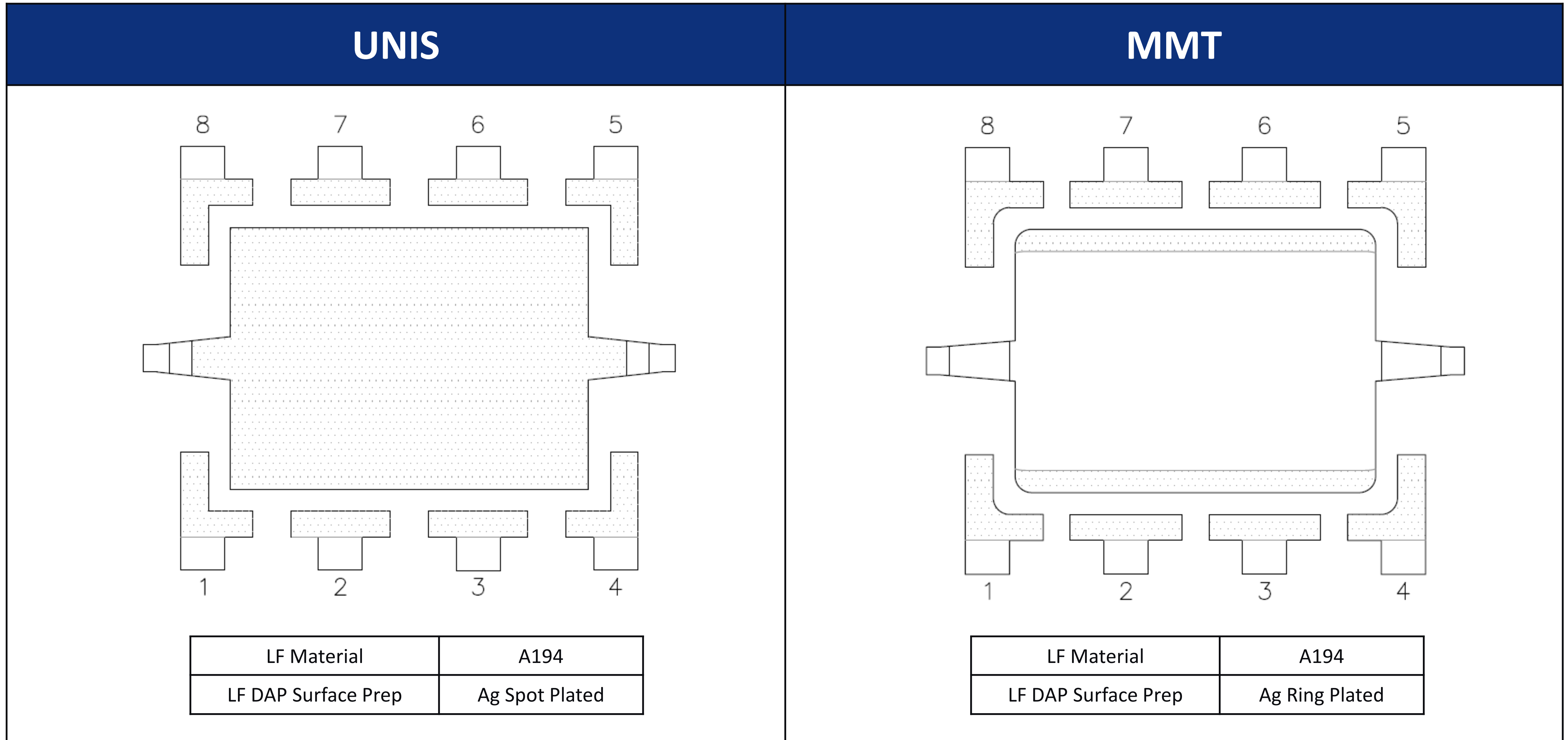
LEAD FRAME COMPARISON



UNIS

LF Material	A194
LF DAP Surface Prep	Ag Spot Plated

MMT

LF Material	A194
LF DAP Surface Prep	Ag Ring Plated

Note: Not to scale

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QUALIFICATION REPORT SUMMARY

RELIABILITY LABORATORY

PCN #: CENO-13CPHA326

Date:
June 19, 2021

Qualification of MMT as an additional assembly site for HV9925SG-G, SR037SG-G, SR036SG-G, CL320SG-G, CL7SG-G, SR087SG-G, SR086SG-G, HV809SG-G, CL325SG-G and CL330SG-G catalog part numbers (CPN) available in 8L SOIC (3.90mm) package. This is a qualification by similarity (QBS) and Q100 Grade 0 qualification.

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PACKAGE QUALIFICATION REPORT

Purpose	Qualification of MMT as an additional assembly site for HV9925SG-G, SR037SG-G, SR036SG-G, CL320SG-G, CL7SG-G, SR087SG-G, SR086SG-G, HV809SG-G, CL325SG-G and CL330SG-G catalog part numbers (CPN) available in 8L SOIC (3.90mm) package. This is a qualification by similarity (QBS) and Q100 Grade 0 qualification.
CN	ES350584
QUAL ID	R2001000 Rev. A
MP CODE	VA9027S7XA01
Part No.	MCP1722-3310H/S7X
Bonding No.	BDE-006378 Rev. 01
CCB No.	4359 and 7197

Package

Type	8L SOIC-EP
Package size	150 mils

Lead Frame

Paddle size	95 x 130 mils
Material	A194
Surface	Double Ag Ring Plating
Process	Etched
Lead Lock	No
Part Number	10100847
Treatment	ME-2

Material

Epoxy	8390A
Wire	Au
Mold Compound	G600V
Plating Composition	Matte Sn

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PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-213202607.000	TC08921225530.200	2045MSS
MMT-213302511.000	TC08921225530.200	20462UD
MMT-213302512.000	TC08921225530.200	20462UE

Result [X] Pass [ ] Fail [ ] ____________________

8L SOIC-EP (150 mils) assembled by MMT pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Precondition Prior Perform Reliability Tests (At MSL Level 1)	**Electrical Test:** +25°C and 150°C System: ETS-88	JESD22-A113	693(0)	693		Good Devices
	Bake 150°C, 24 hrs System: CHINEE	JIP/ IPC/JEDEC J-STD-020E		693		
	85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243			693		
	Electrical Test: +25°C and 150°C System: ETS-88			0/693	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	**Stress Condition:** -55°C to +150°C, 2000 Cycles System: TABAI ESPEC TSA-70H	JESD22-A104		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +150°C System: ETS-88		231(0)	0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (> 2.5 grams)		15 (0)	0/15	Pass	
	Bond Shear (>15.00 grams)		15 (0)	0/15	Pass	
UNBIASED-HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22-A118		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: ETS-88		231(0)	0/231	Pass	77 units / lot
HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. **Bias Volt:** 3.3 Volts System: HAST 6000X	JESD22-A110		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C and 150°C System: ETS-88		231(0)	0/231	Pass	77 units / lot

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	**Stress Condition:** Bake 175°C, 1008 hrs System: SHEL LAB	JESD22-A103		45		45 units
	Electrical Test: +25°C and 150°C System: ETS-88		45(0)	0/45	Pass	
Power Temperature Cycling	**Stress Condition:** -40°C to +150°C, 1000 Cycles System: Votcsh	JESD22-A105		45		45 units
	Electrical Test: +25°C and 150°C System: ETS-88		45(0)	0/45	Pass	
Physical Dimensions	Physical Dimension, 10 units from 1 lot	JESD22-B100/B108	30(0) Units	0/30	Pass	30 units
Bond Strength Data Assembly	Wire Pull (> 4.00 grams)	Mil. Std. 883-2011	30 (0) Wires	0/30	Pass	
	Bond Shear (> 18.00 grams)	CDF-AEC-Q100-001	30 (0) bonds	0/30	Pass	